

L Number	Hits	Search Text	DB	Time stamp
1	29	(MCM or microelectronics) and (AC with coupling) and (inductive or inductors)	USPAT;	2004/05/18
2	24	((MCM or microelectronics) and (AC with coupling) and (inductive or inductors)) and @ad<20011128	US-PGPUB	11:48
3	6	(array with inductors) and (AC with coupling) and @ad<20011128	USPAT;	2004/05/18
4	0	(array with inductors) and (AC with coupling)	US-PGPUB	13:01
5	668	(inductors) and (AC with coupling) and @ad<20011128	USPAT;	2004/05/18
7	662	((inductors) and (AC with coupling) and @ad<20011128) not ((array with inductors) and (AC with coupling) and @ad<20011128)	US-PGPUB	13:03
8	75	((inductors) and (AC with coupling) and @ad<20011128) not ((array with inductors) and (AC with coupling) and @ad<20011128)) and connector	EPO; JPO; DERWENT;	2004/05/18
9	593	((inductors) and (AC with coupling) and @ad<20011128) not (((inductors) and (AC with coupling) and @ad<20011128) not ((array with inductors) and (AC with coupling) and @ad<20011128)) and connector	IBM TDB	13:03
11	248	((inductors) and (AC with coupling) and @ad<20011128) not (((inductors) and (AC with coupling) and @ad<20011128) not ((array with inductors) and (AC with coupling) and @ad<20011128)) and connector)) and (DC with coupling)	USPAT;	2004/05/18
12	8	((inductors) and (AC with coupling) and @ad<20011128) not (((inductors) and (AC with coupling) and @ad<20011128) not ((array with inductors) and (AC with coupling) and @ad<20011128)) and connector)) and (prevent with DC with coupling)	US-PGPUB	14:09
13	240	((inductors) and (AC with coupling) and @ad<20011128) not (((inductors) and (AC with coupling) and @ad<20011128) not ((array with inductors) and (AC with coupling) and @ad<20011128)) and connector)) and (DC with coupling)) not (((inductors) and (AC with coupling) and @ad<20011128) not (((inductors) and (AC with coupling) and @ad<20011128) not ((array with inductors) and (AC with coupling) and @ad<20011128)) and connector)) and (prevent with DC with coupling))	USPAT;	2004/05/18
14	345	((inductors) and (AC with coupling) and @ad<20011128) not (((inductors) and (AC with coupling) and @ad<20011128) not ((array with inductors) and (AC with coupling) and @ad<20011128)) and connector)) not (((inductors) and (AC with coupling) and @ad<20011128) not (((inductors) and (AC with coupling) and @ad<20011128) not ((array with inductors) and (AC with coupling) and @ad<20011128)) and connector)) and (DC with coupling))	US-PGPUB	13:50
15	13	(inductors) and (AC with coupling)	USPAT;	2004/05/18
16	1	("5629838").PN.	EPO; JPO; DERWENT;	14:09
17	6011	257/676,678,684,724,777,778.ccls.	IBM TDB	2004/05/18
			USPAT;	14:25
			US-PGPUB	2004/05/18
			USPAT;	14:30
			US-PGPUB	

18	5	257/676,678,684,724,777,778.ccls. and (AC with coupling)	USPAT; US-PGPUB	2004/05/18 14:29
19	1	257/676,678,684,724,777,778.ccls. and inductors and (AC with coupling)	USPAT; US-PGPUB	2004/05/18 14:31
20	3206	438/106-109.ccls.	USPAT; US-PGPUB	2004/05/18 14:31
21	1	438/106-109.ccls. and inductors and (AC with coupling)	USPAT; US-PGPUB	2004/05/18 14:31

US-PAT-NO: 6261892

DOCUMENT-IDENTIFIER: US 6261892 B1

TITLE: Intra-chip AC isolation of RF
passive components

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Application Filing Date - AD (1):

20001004

Brief Summary Text - BSTX (2):

This invention relates, in general, to integrated circuit structures and fabrication methods and, in particular, to techniques using the etching of porous silicon areas followed by a metal-lined dielectric backfill to provide isolation for circuit components, including decoupling of passive components from the semiconductor substrate to minimize undesirable high frequency AC coupling to and from other components.

Drawing Description Text - DRTX (24):

FIG. 22 is a schematic illustration of the structure of FIG. 21 after inductors have been formed during metallization and a covering dielectric deposited; and